L Number	Hits	Search Text	DB	Time stamp
1	6	(("5094769") or ("5098609") or ("5167851")).PN.	USPAT;	2003/06/05 14:07
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
2	0	((("5094769") or ("5098609") or ("5167851")).PN.) and (compliant	USPAT;	2003/06/05 13:44
	V	NEAR material NEAR metal)	US-PGPUB;	2003/00/03 13:44
		WEAR material WEAR metal)	EPO; JPO;	
			DERWENT;	
		//8500452080	IBM_TDB	
3	0	((("5094769") or ("5098609") or ("5167851")).PN.) and (compliant	USPAT;	2003/06/05 13 44
		NEAR material)	US-PGPUB;	1
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	ř .
4	3	("3778287"   "3885984"   "4265775").PN.	USPAT	2003/06/05 13 51
5	19	5098609.URPN.	USPAT	2003/06/05 13 53
6	0	("thermal\$2NEARconduct\$NEARcompliantNEARmaterial").PN.	USPAT;	2003/06/05 14 08
1		· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	7
]			ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
7	60	thermal\$2 NEAR conduct\$ NEAR compliant NEAR material	USPAT,	2003/06/05 14 43
1	****	mornard2 1432 fit conducto 1432 fit compilate 1422 fit material	US-PGPUB;	2003/05/03/14/43
			ЕРО; ЛРО;	
1			DERWENT;	
0	0	(41, 192 NEAD 140 NEAD1' 4 NEAD1	IBM_TDB	2002/07/05 14 00
8	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) and	USPAT,	2003/06/05 14 09
		(adhes\$3 NEAR metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	43	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) and	USPAT,	2003/06/05 14:09
1		metal	US-PGPUB;	
1			EPO; JPO;	
			DERWENT,	
			IBM TDB	
10	31	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) and	USPAT,	2003/06/05 14:09
		adhes\$3	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT,	
			IBM TDB	
11	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) WITH	USPAT:	2003/06/05 14:44
		(adhes\$ NEAR5 metal)	US-PGPUB:	2005/00/05 17.77
		······································	EPO; JPO;	
			DERWENT;	
			IBM TDB	
12	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) same	USPAT:	2002/06/05 14:44
14	U	(adhes\$ NEAR5 metal)		2003/06/05 14:44
		Taunesa NEARA metal)	US-PGPUB;	
	1		ЕРО; ЛРО;	
			DERWENT,	
12		d do Milab	IBM_TDB	
13	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) WITH	USPAT;	2003/06/05 14:58
		(adhes\$ NEAR metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) same	USPAT;	2003/06/05 14:45
		(adhes\$ NEAR metal)	US-PGPUB,	
			EPO; JPO;	
			DERWENT;	
1				

15	0	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) same	USPAT;	2003/06/05 14:46
		((adhes\$ NEAR (layer film)) NEAR2 metal)	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT:	
			IBM_TDB	
16	2	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) and	USPAT;	2003/06/05 14:58
		((adhes\$ NEAR (layer film)) NEAR2 metal)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	3833	(adhes\$ NEAR (layer film)) NEAR2 metal	USPAT;	2003/06/05 14:48
			US-PGPUB,	
			EPO; JPO;	
			DERWENT;	
	i		IBM_TDB	
18	222	((adhes\$ NEAR (layer film)) NEAR2 metal) and ((thermal heat) NEAR	USFAT;	2003/06/05 14:51
		conduct\$3)	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
19	24	((adhes\$ NEAR (layer film)) NEAR2 metal) and ((thermal heat) NEAR	USPĀT;	2003/06/05 14:51
		conduct\$3 NEAR material\$1)	US-PGPUB;	
		,	FPO; JPO;	
			DERWENT;	
	ĺ		IBM_TDB	
20	60	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material)	USPĀT;	2003/06/05 14:58
		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM TDB	
21	11	(thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) WITH	USPĀT;	2003/06/05 15:01
		metal	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	43	((thermal\$2 NEAR conduct\$ NEAR compliant NEAR material) ) and	USPAT;	2003/06/05 15:01
		metal	US-PGPUB.	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	